

Halogenfree FR4 Laminate: **R-1566(W)**
 Prepreg: **R-1551(W)**

Standard size warp weft mm	Copper foil thickness	Laminate thickness	Thickness tolerance
920 x 1220	0,012 mm	Thin laminates from 0,06 mm up to 0,76mm (excluding Copper foil thickness)	according to IPC - 4101 C B - (C)
1110 x 1220	0,018 mm		
1280 x 1070	0,035 mm	—————	
1240 x 1230*	0,070 mm	Rigid laminates from 0,8 mm up to 1,6 mm (including Copper foil thickness)	according to IPC - 4101 C L - (M)
	0,105 mm		



* Only cut panels Other thicknesses on request

[Features]

- ▶ Halogenfree FR4 material for PCB production
- ▶ A flame-retarding level of UL94 V0 achieved without using halogen flame-retarding agents.
- ▶ Tg: medium Tg class
- ▶ Excellent through-hole conductive reliability, excellent heat resistance
- ▶ Excellent CAF resistance
- ▶ Tracking resistance CTI 500
- ▶ For lead free assembly
- ▶ Conform to the most international standards: IPC-4101C/127, UL94, IPC 4562, UL 946
- ▶ UV-blocking, R-1566W / R-1551W with increased UV-blocking characteristic available
- ▶ Workability: With standard FR4 process

[Applications]

PCs, computer peripherals, cellular phones, digital video cameras, automotive etc